

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t6700mpdcb-2#trmpbf

(Engineering Calculation)

DFN 2mm X 3mm Exp. Pad

(printed on: 2020-07-11 20:43:16)

**TOTAL MASS (g) : 0.015028**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.000567	1000000	37728.7109375		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.005723	975000	380813.78125		
		Iron (Fe)	7439-89-6	0.000141	24000	9382.27246094		
		Phosphorus (P)	7723-14-0	0.000002	300	133.081878662		
		Zinc (Zn)	7440-66-6	0.000004	700	266.163757324		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.005870</b>	<b>1000000</b>	<b>390595.28125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000260	1000000	17323.4335938		
		<b>External Plating Total:</b>				<b>0.000260</b>	<b>1000000</b>	<b>17323.4335938</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000136	1000000	9049.56738281		
<b>Internal Plating Total:</b>				<b>0.000136</b>	<b>1000000</b>	<b>9049.56738281</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000409	750000	27215.2421875		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000136	250000	9049.56738281		
<b>Die Attach Total:</b>				<b>0.000545</b>	<b>1000000</b>	<b>36264.8125</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.000989	130000	65808.984375		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.006545	860000	435510.4375		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000076	10000	5057.11083984		
		<b>Encapsulation Total:</b>				<b>0.007610</b>	<b>1000000</b>	<b>506376.5625</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000040	1000000	2661.63745117		
					<b>TOTAL MASS (g) :</b>	<b>0.015028</b>		